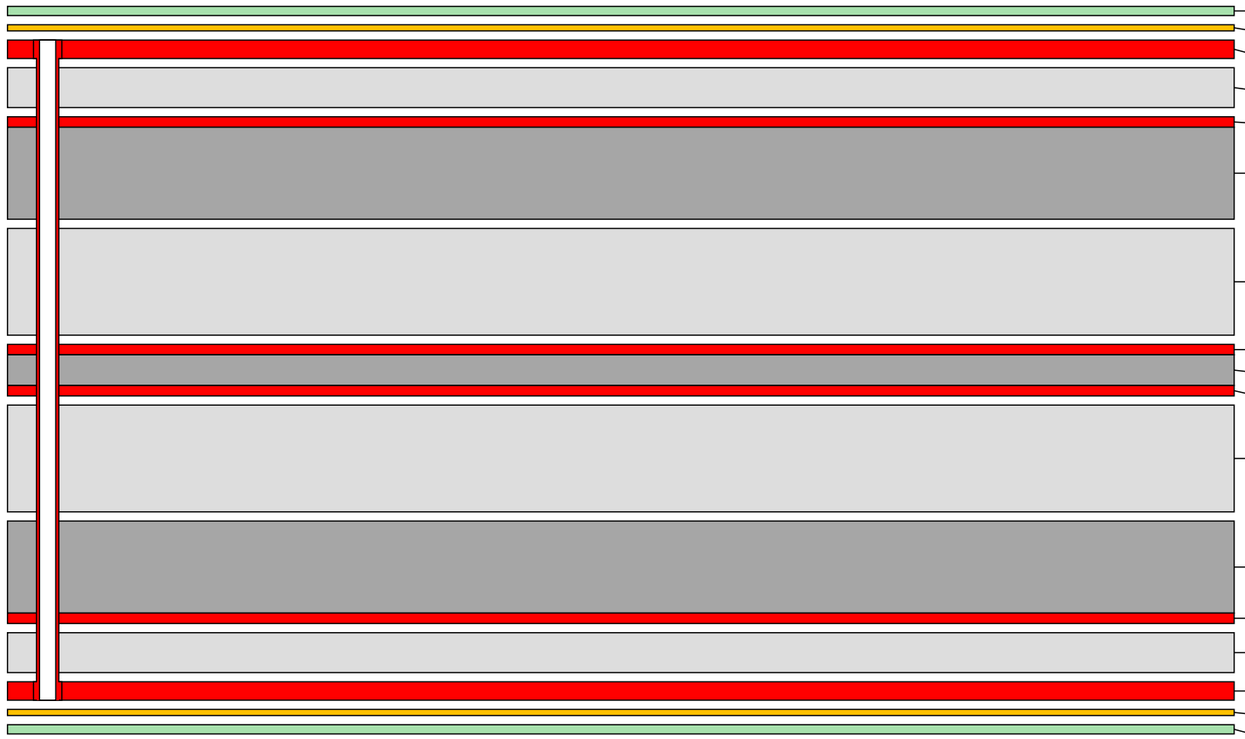
# Rigid



| # | Layer | Thickness | Description | Note |
|---|---|---|---|---|
| | Top Solder | 0.015mm | Soldermask IPC-SM840 | used on rigid parts |
| | Top Surface Finish | 0.006mm | | |
| 1 | Top Side | 0.030mm | Starting foil 1/4oz. after plating and processing | |
| | | 0.065mm | Prepreg IPC-4101/127/128 | FR-4.1 filled, halogen free |
| 2 | Inner Layer 1 | 0.017mm | ED Base Copper | |
| | | 0.150mm | Core IPC-4101/127/128 | FR-4.1 filled, halogen free |
| | | 0.174mm | Prepreg IPC-4101/127/128 | FR-4.1 filled, halogen free |
| 3 | Inner Layer 2 | 0.017mm | ED Base Copper | |
| | | 0.050mm | Flexible core IPC-4204/11 | Flex Polyimide adhesiveless |
| 4 | Inner Layer 3 | 0.017mm | ED Base Copper | |
| | | 0.174mm | Prepreg IPC-4101/127/128 | FR-4.1 filled, halogen free |
| | | 0.150mm | Core IPC-4101/127/128 | FR-4.1 filled, halogen free |
| 5 | Inner Layer 4 | 0.017mm | ED Base Copper | |
| | | 0.065mm | Prepreg IPC-4101/127/128 | FR-4.1 filled, halogen free |
| 6 | Bottom Side | 0.030mm | Starting foil 1/4oz. after plating and processing | |
| | Bottom Surface Finish | 0.006mm | | |
| | Bottom Solder | 0.015mm | Soldermask IPC-SM840 | used on rigid parts |

**Total thickness: 0.997mm**

| | | | | | |
|---|---|---|---|---|---|
| **notes:** | | **FLEX6_2Ri-2F-2Ri_099_17_2V13** | | | |
| **Final copper thicknesses according to IPC-6013** | **Please follow our sectional design rules:<br>► www.we-online.com/designrigidflex** | **PCB Thickness Tolerance: rigid ± 10% / flex ± 0,05mm** | | | |
| | | **customer** | | **created** | |
| **IPC-2223 use A "Flex to install"** | **For impedance matching stackups: Please consult our specialists: FLEX@we-online.com** | **pcb name** | | **approved** | |
| | | **engineer** | | **format** | **A4, landscape** |
| **Standard: Surface Finish ENIG<br>(Ni 5.5 µm ± 1.5 µm, Au 0.075 µm ± 0.025 µm)** | | **date** | | | |
| | | **Template Revision: 10/2023 by Andreas Schilpp / Michael Kress / Werner Öchslen** | | | |

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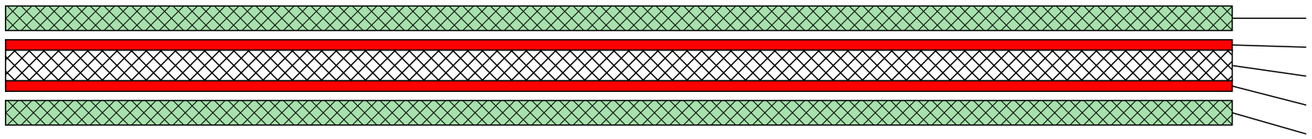
# Flex



| # | Layer | Thickness | Description | Note |
|---|---|---|---|---|
| | Flex Top Coverlay | 0.040mm | PI Coverlay IPC-4203/2 | Polyimide + bonding film (Epoxy) |
| 3 | Inner Layer 2 | 0.017mm | ED Base Copper | |
| | | 0.050mm | Flexible core IPC-4204/11 | Flex Polyimide adhesiveless |
| 4 | Inner Layer 3 | 0.017mm | ED Base Copper | |
| | Flex Bottom Coverlay | 0.040mm | PI Coverlay IPC-4203/2 | Polyimide + bonding film (Epoxy) |

**Total thickness: 0.164mm**

| | | | | | |
|---|---|---|---|---|---|
| **notes:** | | **FLEX6_2Ri-2F-2Ri_099_17_2V13** | | | |
| **Final copper thicknesses according to IPC-6013** | **Please follow our sectional design rules:<br>► www.we-online.com/designrigidflex** | **PCB Thickness Tolerance: rigid ± 10% / flex ± 0,05mm** | | | |
| | | **customer** | | **created** | |
| **IPC-2223 use A "Flex to install"** | **For impedance matching stackups: Please consult our specialists: FLEX@we-online.com** | **pcb name** | | **approved** | |
| | | **engineer** | | **format** | **A4, landscape** |
| **Standard: Surface Finish ENIG<br>(Ni 5.5 µm ± 1.5 µm, Au 0.075 µm ± 0.025 µm)** | | **date** | | | |
| | | **Template Revision: 10/2023 by Andreas Schilpp / Michael Kress / Werner Öchslen** | | | |

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